



Final Product Change Notification

202003036F01

Issue Date: 10-Apr-2020
Effective Date: 09-Jul-2020

Dear *julia wu*,

Here's your personalized quality information concerning products our customers and partners purchased from NXP.
For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Management Summary

NXP is changing the packing format from tray to brick for 30 LPC Microcontroller products.

Change Category

- | | | | | |
|--|---|---|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input checked="" type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC Microcontroller Product Tray to Brick Packing Change

Description of Change

NXP is changing the packing format from single-tray to 5-tray (brick) for 30 LPC Microcontroller products.

This will result in the creation of new part numbers to order and new Minimum Order Quantities (MOQs). A complete list with the new orderable part numbers, including the new packing and MOQ, is attached for your reference.

There is no change to the products, only the packing method and packing quantity.

The Distributor Price Book has been updated with new part numbers.

Upon the effective date of this PCN, NXP will only accept purchase orders for limited quantities of the old (single tray) packing.



Reason for Change

This change will bring significant freight cost savings to our customers by decreasing the use of boxes and shipping volume by 60-80% on average.

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 06-Apr-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 10-May-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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